

## Single N-Channel MOSFET

### DESCRIPTION

SMC2302 is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss are needed in small outline surface mount package.

### PART NUMBER INFORMATION

**SMC 2302 S - TR G**  
 a      b      c      d      e

- a : Company name.
- b : Product Serial number.
- c : Package code            S: SOT-23
- d : Handling code          TR: Tape&Reel
- e : Green produce code G: *RoHS Compliant*

### FEATURES

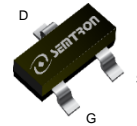
**$V_{DS} = 20V, I_D = 5A$**

$R_{DS(ON)} = 30m\Omega (Typ.) @ V_{GS} = 4.5V$   
 $R_{DS(ON)} = 38m\Omega (Typ.) @ V_{GS} = 2.5V$   
 $R_{DS(ON)} = 50m\Omega (Typ.) @ V_{GS} = 1.8V$

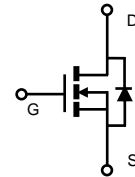
- ◆ Fast switch
- ◆ 1.8V Low gate drive applications
- ◆ Improved dv/dt capability
- ◆ High power and current handling capability

### APPLICATIONS

- ◆ Hand-Held Instruments
- ◆ Load Switch



SOT-23



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units	
$V_{DSS}$	Drain-Source Voltage	20	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 10$	V	
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	5	A
		$T_A = 70^\circ C$	4	A
$I_{DM}$	Pulsed Drain Current <sup>A</sup>	20	A	
$P_D$	Power Dissipation <sup>B</sup>	$T_A = 25^\circ C$	1.3	W
		$T_A = 70^\circ C$	0.8	W
$T_J$	Operation Junction Temperature	-55/150	$^\circ C$	
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ C$	

### THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>B</sup>	$t \leq 10s$	95	$^\circ C/W$
	Thermal Resistance Junction to Ambient <sup>BC</sup>	Steady-State	130	

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ Unless otherwise noted)

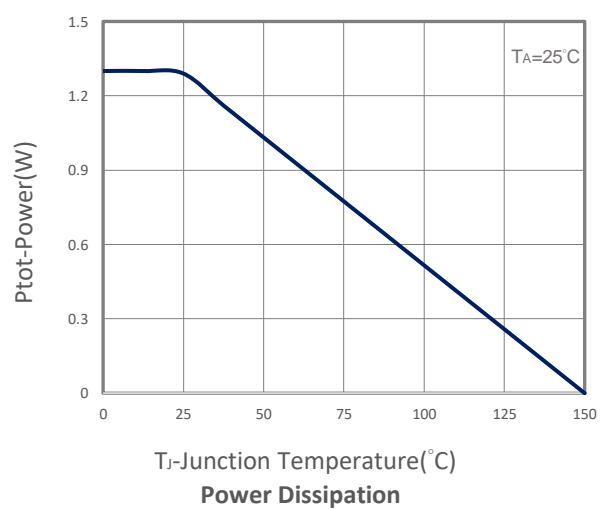
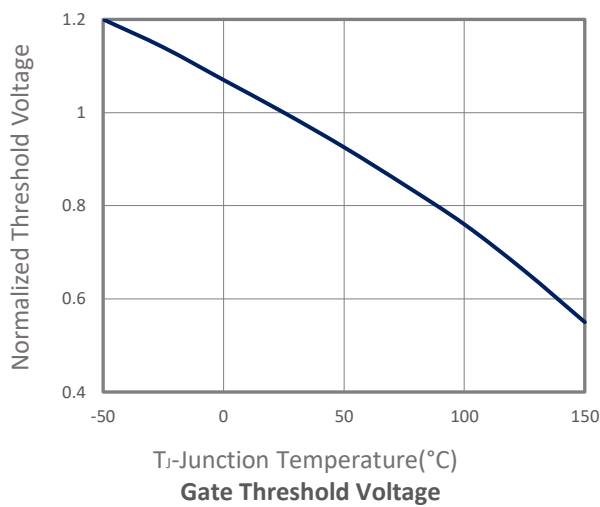
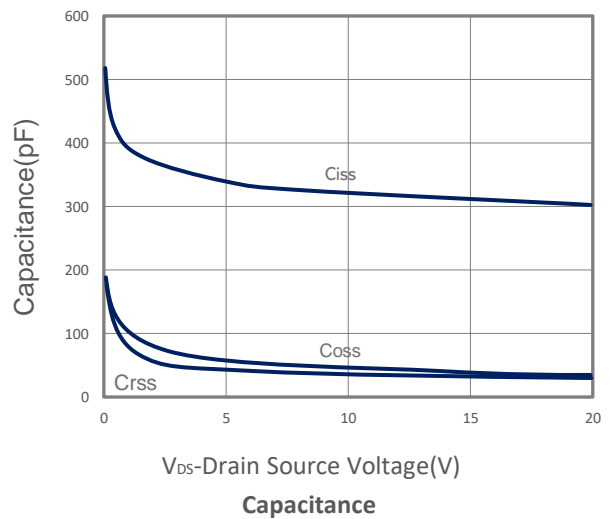
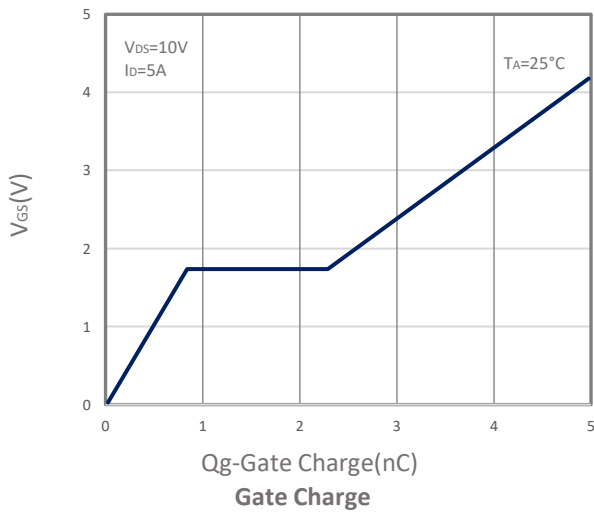
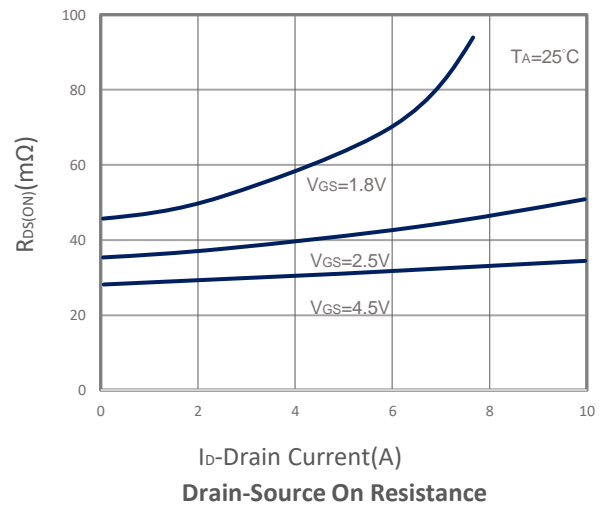
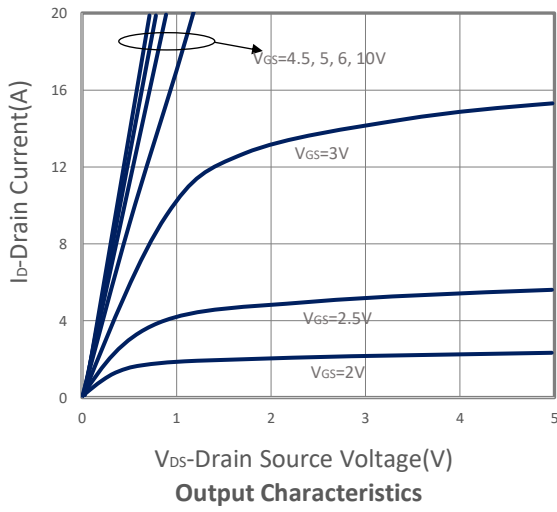
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250 $\mu$ A	20			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 $\mu$ A	0.4	0.6	1	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = $\pm$ 10V			$\pm$ 100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25 $^\circ$ C			1	$\mu$ A
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =75 $^\circ$ C			10	
R <sub>DS(ON)</sub>	Drain-source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A		30	35	m $\Omega$
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =3A		38	45	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =2A		50	60	
G <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =4A		4		S
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.6	1	V
I <sub>S</sub>	Continuous Source Current				2.5	A
<b>Dynamic and Switching Parameters</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A		5.7	8	nC
Q <sub>gs</sub>	Gate-Source Charge			0.8	1.1	
Q <sub>gd</sub>	Gate-Drain Charge			1.5	2.1	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz		305		pF
C <sub>oss</sub>	Output Capacitance			52		
C <sub>rss</sub>	Reverse Transfer Capacitance			43		
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =10V, V <sub>GEN</sub> =4.5V, R <sub>G</sub> =6 $\Omega$ , I <sub>D</sub> =1A		3	6	nS
t <sub>r</sub>				7.8	15	
t <sub>d(off)</sub>	Turn-Off Time			12	23	
t <sub>f</sub>				5.4	10	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

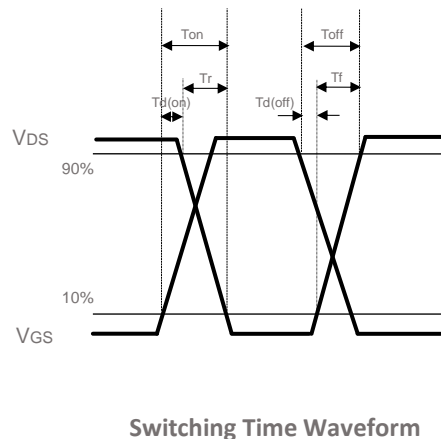
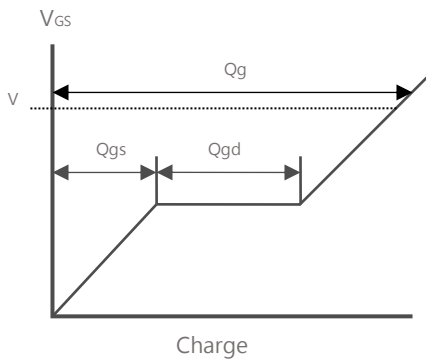
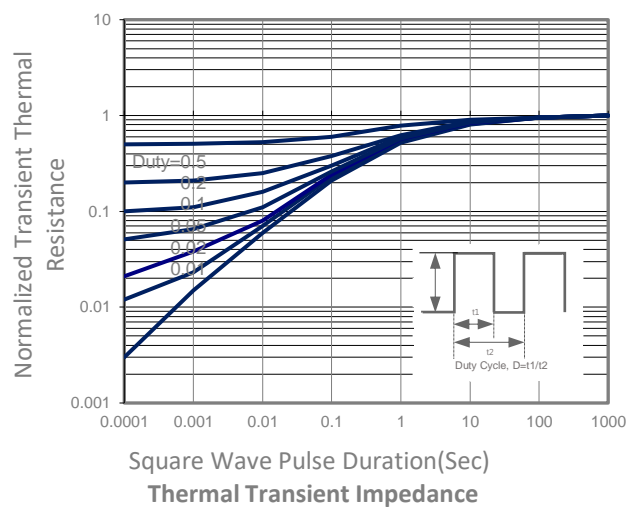
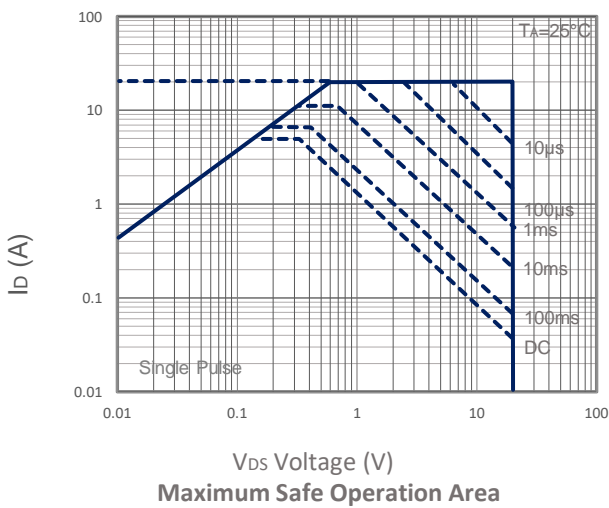
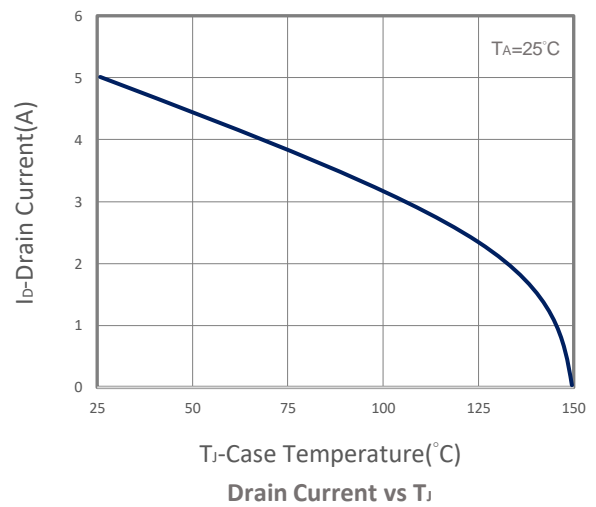
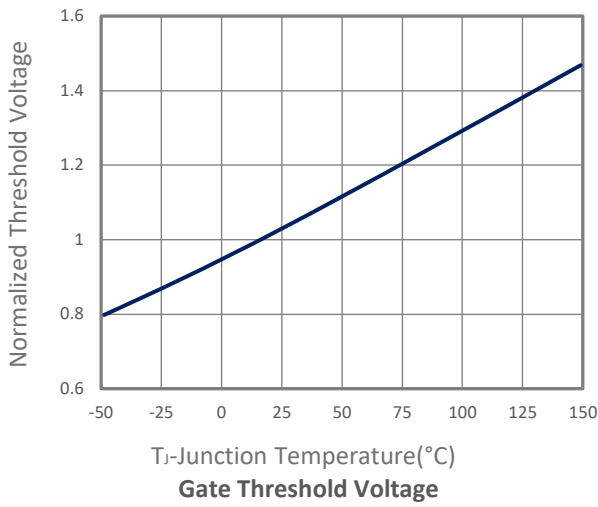
- Pulsed width limited by maximum junction temperature, T<sub>J(MAX)</sub>=150 $^\circ$ C.
- The value of R $\theta$ <sub>JA</sub> is measured with the device mounted on 1in2 FR-4 board in a still air environment with maximum junction temperature T<sub>J(MAX)</sub>=150 $^\circ$ C (initial temperature T<sub>A</sub>=25 $^\circ$ C).
- T<sub>J(MAX)</sub>=150 $^\circ$ C, using junction-to-case thermal resistance (R $\theta$ <sub>JC</sub>) is more useful in additional heat sinking is used.

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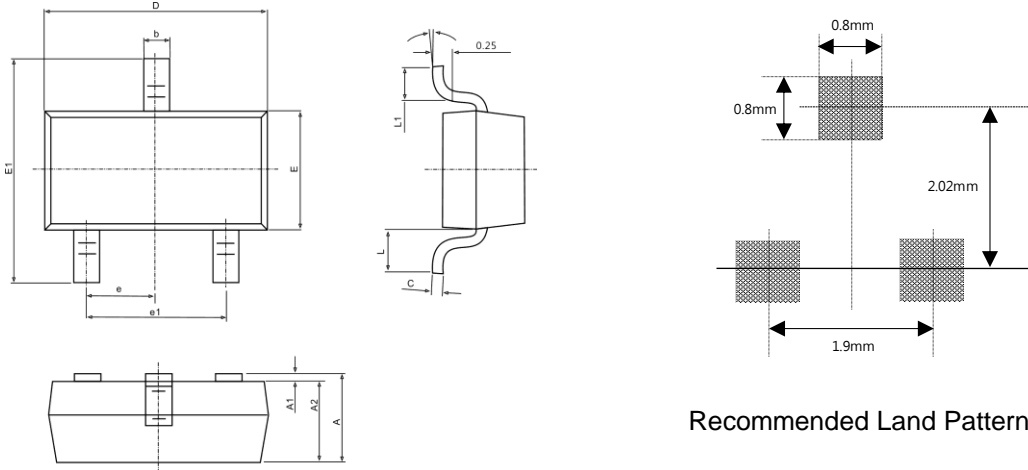
## TYPICAL CHARACTERISTICS



## TYPICAL CHARACTERISTICS



## SOT-23 PACKAGE DIMENSIONS



Recommended Land Pattern

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
$\theta$	0°	8°	0°	8°